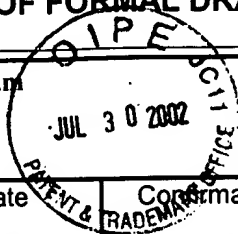


# TRANSMITTAL OF FORMAL DRAWINGS

Docket No.  
MCT.0012D1US (97-0141)

In Re Application Of: **Salman Akram**

COPY OF PAPERS  
ORIGINALLY FILED



Serial No.

Filing Date

Confirmation No.

Examiner

Art Unit

09/853,111

May 10, 2001

7172

Alonzo Chambliss

2827

Invention: **METHOD OF FABRICATING MOUNTED MULTIPLE SEMICONDUCTOR DIES IN A PACKAGE**

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Assistant Commissioner for Patents  
Washington, D.C. 20231

Transmitted herewith are:

3 sheets of formal drawing(s) for this application.

☒ Each sheet of drawing indicates the identifying indicia suggested in 37 CFR Section 1.84(c).

*[Signature]*  
Signature  
**Timothy N. Trop**  
Reg. No. 28,994  
Trop, Pruner & Hu, P.C.  
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Houston, Texas 77024  
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Dated: 7/24/02

I certify that this document and attached formal drawings are being deposited on July 24, 2002 with the U.S. Postal Service as first class mail under 37 C.F.R. 1.8 and addressed to the Assistant Commissioner for Patents, Washington, D.C. 20231.

*[Signature]*  
Signature of Person Mailing Correspondence

**Cynthia L. Hayden**

Typed or Printed Name of Person Mailing Correspondence